



Docket No: TSMC1999-0700/24061.315
Customer Number: 42717

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Issue application of:
Lin

Serial No.: 09/587,465

Filed: 06/05/2000

For: Method of Forming Multilayer
Diffusion Barrier for Copper
Interconnections

§ Attorney Docket: TSMC1999-0700/24061.315
§
§ Confirmation Number: 7855
§
§ Art Unit: 2829
§
§ Examiner: Sarkar, Asok K.
§
§ Notice of Allowance: 05/03/2004
§

Commissioner for Patents
PO Box 1450
Alexandria, VA 22313-1450
MAIL STOP ISSUE FEE

TRANSMITTAL

Dear Sir:

In response to the Notice of Allowance and Issue Fee Due mailed on May 3, 2004, enclosed are the following:

1. Part B - Issue Fee Transmittal (in duplicate);
2. Revocation/New Power of Attorney and Supplemental Sheet (3 pages);
3. "Fee Address" Indication Form (1 page);
4. Check in the amount of \$1330.00; and
5. Return postcard.

The Commissioner is hereby authorized to charge Deposit Account No. 08-1394 for any deficiencies in the enclosed fees. This sheet submitted in duplicate.

Respectfully submitted,

T. F. Bliss

Timothy F. Bliss
Registration No. 50,925

Date: 8/2/04
HAYNES AND BOONE, LLP
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R81445.1

I hereby certify that this correspondence is being deposited
with the United States Postal Service as first class mail in an
envelope addressed to: Commissioner for Patents
PO Box 1450, Alexandria, VA 22313-1450

on

8-2-04

Bonnie Boyle
Bonnie E. Boyle